IN THE CLAIMS:

The following is a complete listing of the claims, reflects all changes currently being made thereto, and replaces all prior versions and listings of claims in the present application:

1. to 8. (Canceled)

9. (Currently Amended) A light emitting diode, comprising:

at least one light emitting diode die, arranged on a light emitting diode printed circuit board by means of a die attach, the light emitting diode printed circuit board comprising at a lower surface thereof rear side contacts, wherein the rear side contacts of the light emitting diode printed circuit board at least partially overlap with contours of the light emitting diode die and are formed in such a way as to overlap with at least half of the lower surface of the light emitting diode printed circuit board, and

wherein the light emitting diode printed circuit board comprises a plurality of ~~through-contacts~~ conductive through-vias in the light emitting diode printed circuit board, the through-vias thermally and electrically connecting the rear side contacts of the light emitting diode printed circuit board to contact areas formed on an upper surface of the light emitting diode printed circuit board.

10. (Currently Amended) The light emitting diode of claim 9, wherein the light emitting diode printed circuit board is a metal core printed circuit board having a metal core, and wherein the light emitting diode die is located on the metal core.

11. (Withdrawn) A light emitting diode according to claim 9, wherein the light emitting diode printed circuit board is a metal core printed circuit board and wherein a non-linear isolator material layer is arranged between at least one of the contact areas and the metal core printed circuit board.

12. (Previously Presented) The light emitting diode of claim 9 or 10, wherein the light emitting diode die is mounted face down to the light emitting diode printed circuit board.

13. (Currently Amended) A light emitting diode light source comprising:

at least one light emitting diode, wherein each [[said]] light emitting diode comprises at least one light emitting diode die, arranged on a light emitting diode printed circuit board by means of a die attach, the light emitting diode printed circuit board comprising at a lower surface thereof rear side contacts, wherein the rear side contacts of the light emitting diode printed circuit board at least partially overlap with contours of the light emitting diode die and wherein the rear side contacts of the light emitting diode printed circuit board ~~are formed in such a way as to~~ overlap with at least half of the lower surface of the light emitting diode printed circuit board, and wherein the light emitting diode printed circuit board comprises a plurality of ~~through-contacts~~ conductive through-vias in the light emitting diode printed circuit board, the through-vias thermally and electrically connecting the rear side contacts to contact areas formed on an upper surface of

the light emitting diode printed circuit board, [[said]] the light emitting diode being arranged on an additional board,

wherein the additional board comprises on an upper surface thereof further contact areas which are soldered to the rear side contacts of the light emitting diode printed circuit board,

wherein a total surface area of the further contact areas is at least half of the area of the lower surface of the light emitting diode printed circuit board, and

wherein the additional board comprises a further plurality of ~~through-contacts~~ conductive through-vias in the additional board, the through-vias thermally and electrically connecting at least one of the further contact areas to a solder area formed at a lower surface of the additional board.

14. (Withdrawn) A light emitting diode light source according to claim 13, wherein a cooling body is located at a rear side of the additional board.

15. (Currently Amended) The light emitting diode light source of claim 13, wherein at least one of the plurality of ~~through-contacts~~ through-vias of the light emitting diode printed circuit board and at least one of the further plurality of ~~through-contacts~~ through-vias of the additional board have a diameter of less than 100 μm.